



ZXMP6A16DN8

Product Summary

BV _{DSS}	R _{DS(ON)} Max	Package	I _D T _A = +25°C (Notes 4 & 6)
601/	$\frac{85 \text{m} \Omega @ V_{\text{GS}} = -10 \text{V}}{125 \text{m} \Omega @ V_{\text{GS}} = -4.5 \text{V}}$		-3.9A
-60 V			-3.2A

Description

This MOSFET has been designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- DC-DC Converters
- Power Management Functions
- Disconnect Switches
- Motor Control

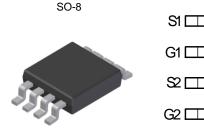
Features

- Low On-Resistance
- Fast Switching Speed
- Low Threshold
- Low Gate Drive
- Low Profile SOIC Package
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- An Automotive-Compliant Part is Available Under Separate Datasheet (ZXMP6A16DN8Q)

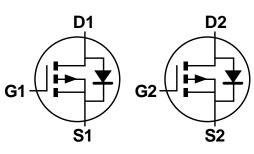
DUAL P-CHANNEL 60V ENHANCEMENT MODE MOSFET

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.074 grams (Approximate)



○ □ D1 □ D1 □ D2 □ D2



Equivalent Circuit

Ordering Information (Note 4)

Top View

Part Number	Case	Packaging
ZXMP6A16DN8TA	SO-8	500/Tape & Reel
ZXMP6A16DN8TC	SO-8	2,500/Tape & Reel

1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.

Top View

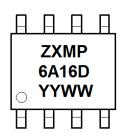
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



ZXMP6A16D = Product Type Marking Code YYWW = Date Code Marking YY = Year (ex: 16 = 2016) WW = Week (01 - 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Ch	aracteristic		Symbol	Value	Unit V
Drain-Source Voltage			V _{DSS}	-60	
Gate-Source Voltage		(Note 5)	V _{GS}	±20	V
		(Notes 7 & 9)		-3.9	
Continuous Drain Current	V _{GS} = 10V	T _A = +70°C (Notes 7 & 9)	ID	-3.1	А
		(Notes 6 & 9)		-2.9	
Pulsed Drain Current		(Notes 8 & 9)	IDM	-18.3	А
Continuous Source Current (Body Diode)		(Notes 7 & 9)	Is	-3.2	А
Pulsed Source Current (Body Diode)		(Notes 8 & 9)	I _{SM}	-18.3	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit		
	(Notes 6 & 9)		1.25 10.0		
Power Dissipation Linear Derating Factor	(Notes 6 & 10)	PD	1.81 14.5	W mW/°C	
	(Notes 7 & 9)		2.15 17		
	(Notes 6 & 9)		100		
Thermal Resistance, Junction to Ambient	(Notes 6 & 10)	R _{0JA}	70	0044/	
	(Notes 7 & 9)		60	°C/W	
hermal Resistance, Junction to Lead (Notes 9 & 11)		R _{θJL}	48.85		
Operating and Storage Temperature Range	TJ, T _{STG}	-55 to +150	°C		

Notes: 5. AEC-Q101 VGS maximum is $\pm 16V$.

6. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.

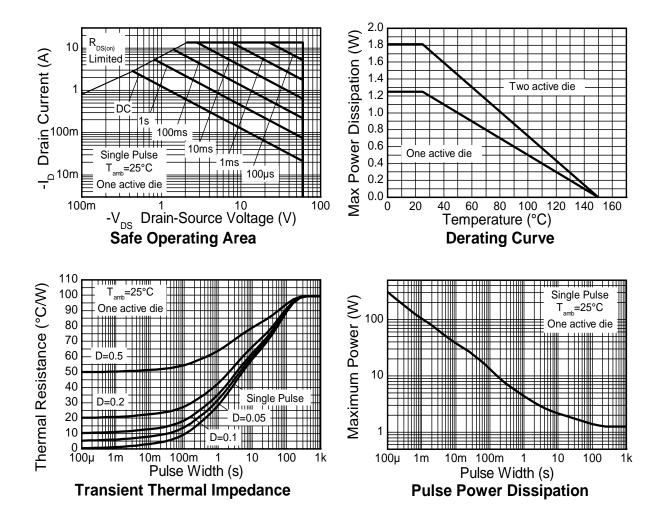
7. Same as Note (5), except the device is measured at t \leq 10 sec. 8. Same as Note (5), except the device is pulsed with D = 0.02 and pulse width 300µs.

9. For a dual device with one active die.

10. For a device with two active die running at equal power.
11. Thermal resistance from junction to solder-point.



Thermal Characteristics (Continued)





Notes:

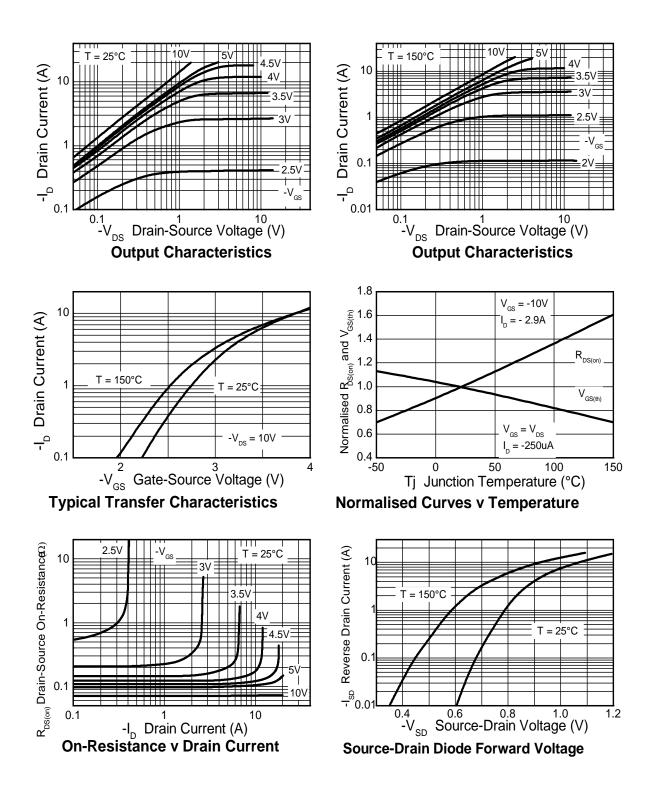
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test	Condition
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	-60	—	—	V	$I_D = -250 \mu A, V_{GS} = 0 V$	
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1.0	μA	$V_{DS} = -60V, V_{OS}$	GS = 0V
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(TH)}	-1.0	_	_	V	I _D = -250μA, V	ds = Vgs
Static Drain-Source On-Resistance (Note 12)	р		_	85	mΩ	V _{GS} = -10V, I _D = -2.9A	
Static Drain-Source On-Resistance (Note 12)	R _{DS(ON)}	_	_	125	11122	$V_{GS} = -4.5V, I_{E}$	₀ = -2.4A
Forward Transconductance (Notes 12 & 13)	g fs	_	7.2	—	S	V _{DS} = -15V, I _D = -2.9A	
Diode Forward Voltage (Note 12)	V _{SD}		-0.85	-0.95	V	I _S = -3.4A, V _{GS} = 0V, T _J = +25°C	
Reverse Recovery Time (Note 13)	t _{RR}	_	29.2	_	ns	I _S = -2A, di/dt = 100A/μs, T _J = +25°C	
Reverse Recovery Charge (Note 13)	Q _{RR}	_	39.6	—	nC		
DYNAMIC CHARACTERISTICS (Note 14)							
Input Capacitance	CISS	_	1,021	_	pF	$V_{DS} = -30V, V_{GS} = 0V,$ = f = 1MHz	
Output Capacitance	C _{OSS}	_	83.1	_	pF		
Reverse Transfer Capacitance	C _{RSS}	_	56.4	_	pF		
Total Gate Charge	Q _G	_	12.1	_	nC	$V_{GS} = -5V$	
Total Gate Charge	Q _G	_	24.2	_	nC	$V_{\rm GS} = -10V$ $V_{\rm DS} = -30V,$ $V_{\rm D} = -2.9A$	
Gate-Source Charge	Q _{GS}	_	2.5	_	nC		
Gate-Drain Charge	Q _{GD}		3.7	_	nC		
Turn-On Delay Time	t _{D(ON)}		3.5	_	ns	$V_{DD} = -30V, V_{GS} = -10V,$ $I_D = -1A, R_G \cong 6.0\Omega$	
Turn-On Rise Time	t _R		4.1	_	ns		
Turn-Off Delay Time	t _{D(OFF)}		35	_	ns		
Turn-Off Fall Time	t _F	_	10	_	ns		

Measured under pulsed conditions. Pulse width ≤ 300µs; duty cycle ≤ 2%
For design aid only, not subject to production testing.
Switching characteristics are independent of operating junction temperatures.

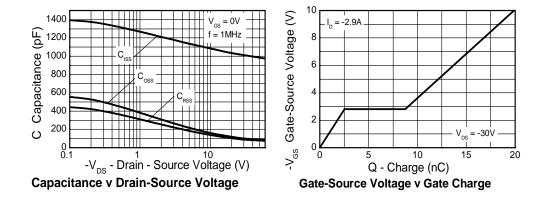


Typical Characteristics

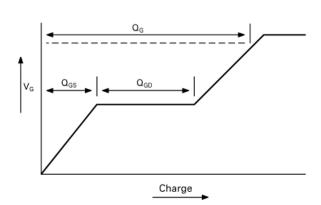




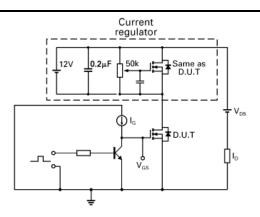
Typical Characteristics (Continued)



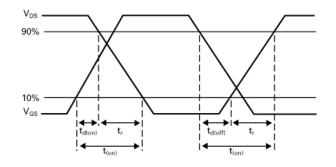
Test Circuits

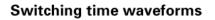


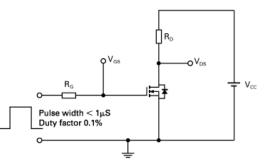
Basic gate charge waveform



Gate charge test circuit





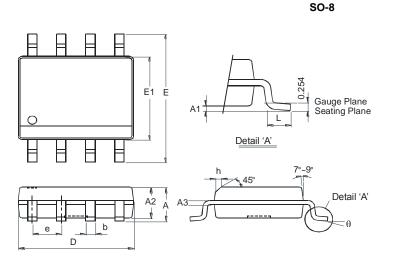


Switching time test circuit



Package Outline Dimensions

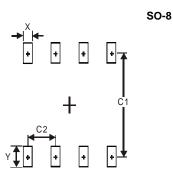
Please see http://www.diodes.com/package-outlines.html for the latest version.



SO-8					
Dim	Min	Max			
Α	-	1.75			
A1	0.10	0.20			
A2	1.30	1.50			
A3	0.15	0.25			
b	0.3	0.5			
D	4.85	4.95			
Е	5.90	6.10			
E1	3.85	3.95			
e	1.27 Тур				
h	-	0.35			
L	0.62	0.82			
θ	0°	8°			
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27

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